

1-9. (canceled)

10. (original) An improved mushrooms for bumping of a semiconductor product having a series closely space connections comprising:

a stem extending from the closely spaced connections on the semiconductor product;
and

an elongated mushroom extending from said stem;
said elongated mushroom having a short axis in the direction of adjacent connection mushrooms to be bumped and a long axis orthogonal to the short axis to increase the volume of solder to be reflowed and produce a larger diameter/taller solder ball than with a circular mushroom.

Please add the following new claims:

11. The structure of claim 10 wherein said stem is circular.

12. The structure of claim 11 wherein said circular stem is copper.

13. The structure of claim 10 wherein said elongated mushroom is elliptical.